



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Christo P. Bojkov, et al.

Serial No.: 10/689,386

Filed: 10/20/03

For: Direct Bumping on Integrated Circuit Contacts Enabled by Metal-to-Insulator Adhesion

TI-35951

Examiner: TBD

Art Unit: TBD

LETTER TO THE OFFICIAL DRAFTSPERSON

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)  
I hereby certify that the above correspondence is being deposited with the  
U.S. Postal Service as First Class Mail in an envelope addressed to:  
Commissioner of Patents, P.O. Box 1450, Alexandria, VA, 22313-1450.

Karen Vertz      1-30-04  
Karen Vertz      Date

Commissioner for Patents

P. O. Box 1450

Alexandria, VA 22313-1450

Sir:

Enclosed are **TWO (2)** sheets of formal drawings for the above-referenced case. Please charge any necessary fees to Deposit Account No. 20-0668 of Texas Instruments Incorporated. This sheet is enclosed in triplicate.

Respectfully submitted,

W. James Brady, III  
Attorney for Applicants  
Reg. No. 32,080

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